In the Specification:

Please make the following changes at the indicated locations in the indicated specification paragraphs:

Page 3, lines 7 to 15:

According to the invention the contact element electrically connects the wave guide with the conductor strip by means of two contacting areas <u>of the contact element</u> and is made from an accurately prefabricated <u>leaf</u> ~~coil~~ spring having predetermined reproducible properties. This <u>leaf</u> ~~coil~~ spring is connected at one of the contacting areas to the conductor strip or to the wave guide by means of an electrically conductive glue and <u>a sliding contact is provided at the other contacting area and the spring</u> ~~another of the contacting areas is a sliding contact whereby the coil spring~~ is pre-tensioned<u>,</u>[[;]] or <u>the leaf spring is connected at the other contacting area</u> ~~is provided~~ by an electrically conductive glue or adhesive portion <u>and</u> [[,]] ~~whereby~~ the <u>leaf</u> ~~coil~~ spring is bent into a U-shape[[;]]<u>,</u> or <u>the leaf spring is connected at the other contacting area by</u> ~~is provided with a~~ highly flexible electrically conductive adhesive section.

Page 4, lines 10 to 16:

The <u>leaf</u> ~~coil~~ spring for applications in high-frequency engineering is especially small (length, about 100 to 200 μm, thickness about 50 μm). The <u>leaf</u> ~~coil~~ spring is formed with very great accuracy, particularly as a so-called MIGA

leaf ~~coil~~ spring (MIGA means microgalvanic). UV depth lithography or comparable methods of structuring polymers in combination with multilayer microgalvanic methods are suitable for making the leaf ~~coil~~ spring. Laser processing or high precision punching or stamping can be suitable for making the leaf ~~coil~~ spring.

Page 4, lines 17 to 23:

Thus simple but precise or exact fabrication methods are possible for the ~~coil~~ leaf spring. Tolerances of < ±10 μm may be obtained for the above-described contact element with UV depth lithography. A wide range of materials can be selected so that special spring properties can be obtained. An automatic mounting of the ~~coil~~ leaf spring and easy manufacture of the electrical connection are possible. Several ~~coil~~ leaf springs can be economically made at the same time in a batch process (which means for many applications).

Page 6, line 12, to page 7, line 2:

According to figure 1, a ~~coil~~ leaf spring 11 operating as an electrically conductive contact element is bonded to the conductor strip 7 at a first contacting area 9 with an electrically conducting glue or adhesive. Silver-filled epoxy resin glue is suitable as the adhesive material. The wave guide 1 is assembled after the ~~coil~~ leaf spring 11 has been bonded with the adhesive, so that the mechanically pre-tensioned ~~coil~~ leaf spring 11, which forms a sliding contact 10 at a second contacting area 9', presses resiliently against an exterior surface 1a

of the wave guide 1, which extends substantially perpendicularly to the plane of the conductor strip 7. The contact element forms a low impedance contact between the wave guide 1 and the conductor strip 7. The low impedance connection is required in order to permit an optimum tuning of the coupling of the electromagnetic waves from the wave guide 1 into the conductor strip 7. Besides the geometry of the junction plays an important role.

Page 7, lines 3 to 7:

Relative motions, especially thermally dependent relative motions, between the wave guide 1 and the conductor strip 7 are compensated with the help of the sliding contact 10 and the spring force of the ~~coil~~ leaf spring 11. Without this device, the contacting areas would be subjected to impermissibly large mechanical stresses.

Page 7, lines 8 to 11:

Figure 2 illustrates another embodiment for the ~~coil~~ leaf spring 12. This embodiment is similar to the embodiment shown in Fig. 1, but differs from it because the surface 1b of the wave guide 1 on which the ~~coil~~ leaf spring 12 bears is substantially parallel to the conductor strip 7 and inside the coupling opening 8 of the wave guide. In this embodiment also the ~~coil~~ leaf spring 12 acting as contact element is fixed to the conductor strip 7 at a first contacting area 9 by an electrically conductive adhesive. Similarly the ~~coil~~ leaf spring 12

bearing on the surface 1b of the wave guide 1 at the other contacting area 9' forms a sliding contact 10 in electrical contact with the wave guide 1.

Page 7, lines 12 to 16:

This latter situation in regard to Fig. 2 is also true of the third embodiment shown in Fig. 3. In the embodiment shown in Fig. 3, the ~~coil~~ leaf spring 13 is bonded to the conductor strip 7 at a first contacting area 9 with an electrically conductive glue or adhesive. The sliding contact 10 of the ~~coil~~ leaf spring 13 with the wave guide 1 is located at another contacting area 9' in a cavity 1c of the wave guide 1. It is also possible to additionally secure the spring contact in the cavity with a highly flexible electrically conductive glue or adhesive material.

Page 7, lines 17 to 19:

In the embodiment shown in Fig. 4, a ~~coil~~ leaf spring 14 is electrically conductively glued to the wave guide 1 at one contacting area 9, while the sliding contact 10 makes electrical contact on the conductor strip 7 on the other conducting area 9'.

Page 7, line 20, to page 8, line 2:

In Figure 5, in a fifth embodiment, the ~~coil~~ leaf spring 15 has a curved U-shape. A first contacting area 9 of the ~~coil~~ leaf coil spring 15 is glued in an electrically conductive manner to the conductor strip 7. The other contacting area 9' of the ~~coil~~ leaf spring 15 is formed as an electrically conducting adhesive area

16. This adhesive area 16 can however be highly flexible. The ~~coil~~ leaf spring 15 need not then be formed so that it is U-shaped.